

The logo consists of a red square with a small white square inside it, followed by the word "innodisk" in white lowercase letters.

innodisk

Innodisk Corporate Investor Conference (Symbol: 5289)

Randy Chien, Chairman 2025.11.24

DISCLAIMER

This file and the financial information and forecast information are based on information obtained by the company from internal and external sources. The actual operating results and financial conditions of the company may differ from these predictive sets of information due to various uncontrollable factors.

The viewpoints in this file reflects the company's opinion on the future by the current date. If there are any changes or adjustment in the future, the company is not responsible for notifying the reader or updating the content.

AGENDA

- Company Profile and Overview
- Market Trend and Product Strategy
- AI in Action Global Campaign
- ESG Commitment
- Financial Information
- Q&A

COMPANY PROFILE & OVERVIEW

FOUNDED

2005

2025 MARKS
INNODISK'S 20TH ANNIVERSARY

REVENUE

NT\$9.45B
(2025Q3)

CAPITAL

NT\$953M

EPS

NT\$12.46
(2025Q3)

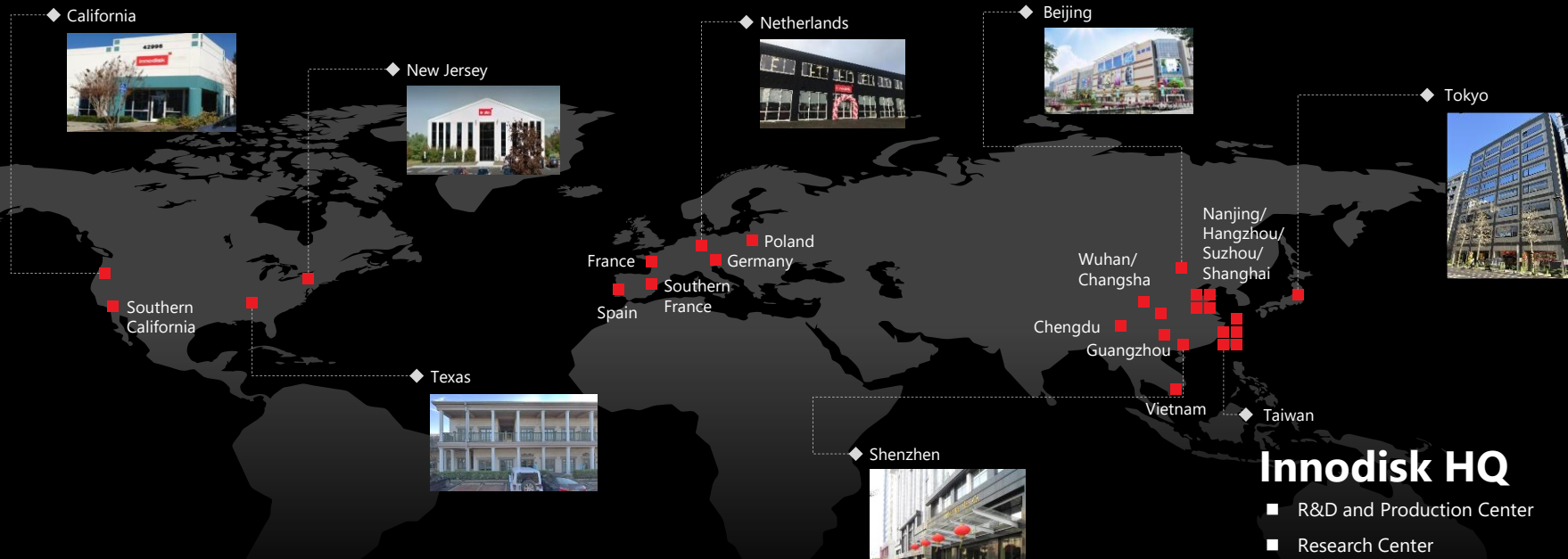
PATENTS

197 (+5)

CUSTOMERS

4,000+

GLOBAL BUSINESS OPERATIONS



Locations

25

Employees

1,139

Taiwan: 998 / Overseas: 141



innodisk

Lot Size
(Sq. Meter)

27,000

Floor Area:
1st building (Sq. Meter)

12,000

2025 Capacity
(SMT x 6)

900K

Maximum Capacity
(SMT x 8)

1,200K

Floor Area:
2nd building (Sq. Meter)

15,000

▶ Edge AI System and Solution
Edge AI Embedded Peripheral
Edge AI Camera Module



YILAN R&D AND MANUFACTURING CENTER



SPACE

Total :19,800 m²**17F** 1,650 m² (Aetina)**16F** 3,300 m²**7F** 3,300 m² (Aetina 660 m²)**5F** 3,300 m²**4F** 3,300 m²**3F** 3,300 m²**2F** 1,320 m² (Aetina 660 m²)**INNODISK HEADQUARTER**



PRODUCTION

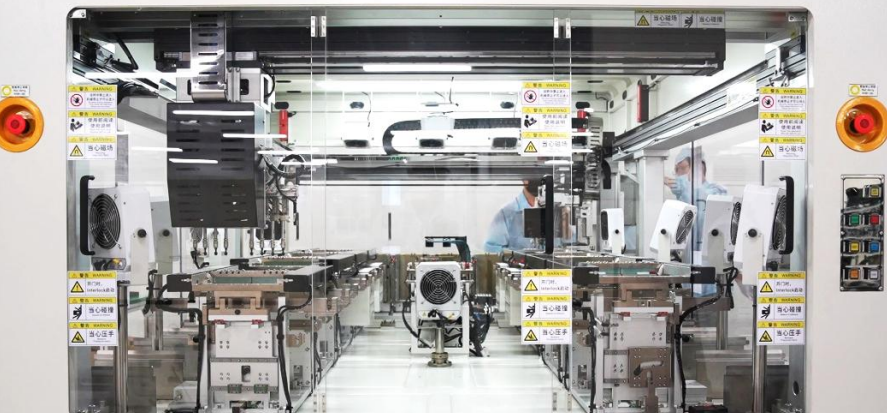
1,350K / Monthly (2025)

CERTIFICATIONS

**ISO9001 / ISO14001 / ISO45001 /
QC080000 / ISO14064-1 / ISO27001**

MANUFACTURING

New Taipei City / Yilan County

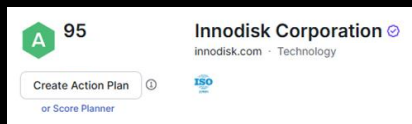


QUALITY & SUSTAINABILITY: OUR TOP PRIORITY

ZERO-TRUST NETWORK SECURITY RESILIENCE

- To address geopolitical shocks and enhance the company's information resilience, we are building a cloud-ground integrated application architecture.
- Deploy information security protection - R&D, manufacturing, and backend
- Complete Xizhi / Yilan Information Service Maintenance Support Center
- Refine information service operation methods (authority, data management, processing timeliness) and implement education and training to enhance the information literacy of colleagues

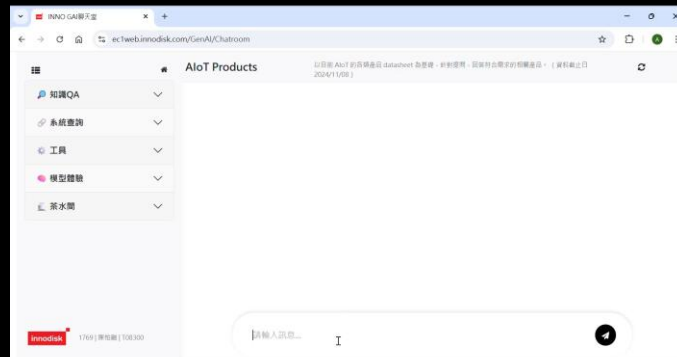
ICT SECURITY



- Maintained **A level** under 3rd party verification
- Under ESG Committee to strengthened, and overall sustainability governance will be improved.
- Passed ISO27001 certification and joined alliances such as TWCERT/CC and IoT Internet Industry Association collaborating to enhance cybersecurity protection

GAI DEPLOYMENT INTELLIGENT INTEGRATION

- Intelligent innovation under information security risks are controllable
- Use of GAI technology in the field to achieve intelligent/efficient professional and efficient implementation
- By leveraging diverse third-party technical resources, the company can deepen its integration and application of GAI/ML/RPA technologies.
- Projects to continue ESG sustainable IT:
 - Procurement of hardware devices and data deployment from IT to implement sustainable IT
 - Adapting cloud applications to maximize energy efficiency and carbon emissions reduction



STRENGTHEN CYBERSECURITY RESILIENCE

PARTNERSHIP AND AWARDS

Partner



Official Intel
Gold Partner



NVIDIA Elite Partner (Aetina)
MGX Partner (Aetina)



Qualcomm
IoT Partner



Official partner of
Azure Sphere



AI ASIC & NPU
Partner

Achievements

Gartner

World's TOP 1
Industrial Grade SSD Provider

TRENDFORCE

World's TOP 10
DRAM Module Provider

Interbrand

TOP 40 International
Taiwanese Brand

Forbes

Asia's 200 Best Companies
Under A Billion

Innovation



2025 ~ 2026 **E3.L PCIe Gen5 Data Center SSD**
2025 ~ 2026 **LPDDR5X LPCAMM2**
2025 ~ 2026 **MIPI over Type-C Camera Module**
2025 ~ 2026 **Edge AI System** (APEX-P200)
2025 ~ 2026 **AI Agent Edge Workstation** (AIP-FR68S)
2025 ~ 2026 **Multi-Accelerator Edge AI System** (AIP-MURE)



2025 **MIPI over Type-C Camera**
2025 **E3.L 5QS-P Data Center SSD**
2024 **E1.S 4TG2-P SSD**
2023 **nanoSSD**



2025 **CXL Memory Module**
2022 **Ultra Temp. DDR4 DRAM**



2024 **USB Camera Module**



**E3.L PCIe Gen5
Data Center SSD**



**LPDDR5X
LPCAMM2**



**MIPI over Type-C
Camera Module**



Edge AI System
APEX-P200



aetina

AI Agent Edge Workstation
AIP-FR68S



aetina

Multi-Accelerator Edge AI System
AIP-MURE

MARKET TREND & PRODUCT STRATEGY

INDUSTRIAL PC
MARKET

VERTICAL
MARKET (IIoT)

SMART VERTICAL
MARKET (AIoT)

EDGE AI MARKET



Smart Energy

Retail & Logistics

Transportation

Enterprise

Healthcare

Aerospace

Edge Server

Communication

Manufacturing

IT Service

Surveillance

Entertainment

Industrial and Vertical AI



Enterprise AI



FROM CLOUD TO THE EDGE

Focusing on Industry and
Enterprise Edge AI

Gemini



deepseek

meta-llama

CLOUD AI

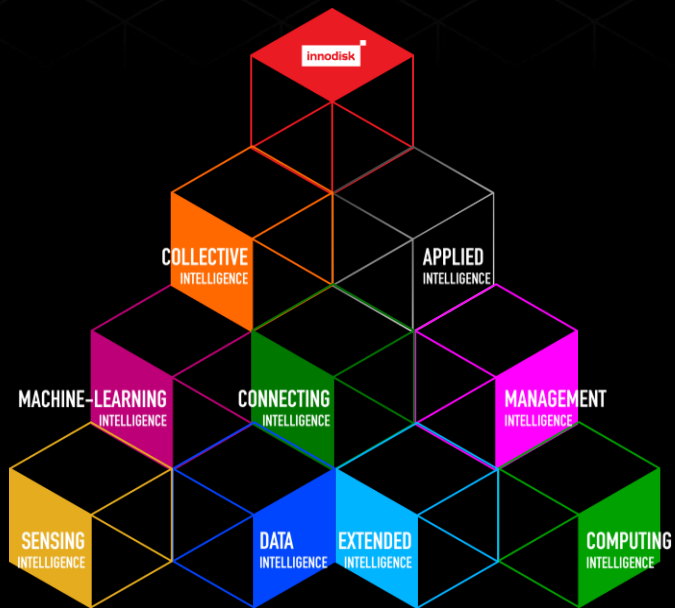
INDUSTRY EDGE AI

ENTERPRISE EDGE AI



INTELLIGENCE BUILDING BLOCKS

Innodisk Comprehensive Edge AI Portfolio



ARCHITECT INTELLIGENCE

SOFTWARE / FIRMWARE	Cloud AI Platform			
	AI Stack SDK			
	Software Tool			
	Operating System			
AI ACCELERATOR	NVIDIA		Qualcomm	
	Intel		AI ASIC	
AI PLATFORM	x86			
	Arm			
EMBEDDED PERIPHERAL	Flash	Display	LAN	GNSS
	DRAM	Storage	CANbus / CANFD	Wireless
SENSOR	Embedded Camera Module			
	Air Sensor			



SENSING INTELLIGENCE CAMERA MODULE NEW PRODUCT OVERVIEW



**GMSL
CAMERA MODULES**



**MIPI over Type C
CAMERA MODULES**

PRODUCT FEATURE

- Provides versatile mounting designs for easy integration into vehicle systems
- Offers IP67 protection with optional IK10 impact resistance
- Implement ADI MAXIM GMSL SerDes to extend service range up to 15M
- High bandwidth, low latency
- ISP inside, optimized image quality
- Support the latest NVIDIA Jetson / Raspberry Pi platform

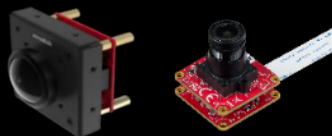


- Honored with the Taiwan Excellence Award
- Offering options of with and without housing; rugged design and easy installation
- Customized Type-C cable to extend MIPI service distance
- High bandwidth, low latency
- ISP inside, optimized image quality
- Low light & HDR features are idea for embedded applications
- Support the latest NVIDIA Jetson / Intel / Raspberry Pi platform



SENSING INTELLIGENCE

CAMERA MODULES FULLY DRIVER-SUPPORTED



MIPI CSI-2 Series Camera Module



MIPI over Type-C Series Camera Module

NVIDIA



Jetson
AGX Orin



Jetson
Orin NX / SUPER



Jetson
Orin Nano / SUPER

Intel



Intel® Core™
Ultra processor



Raptor Lake
13th Gen



Alder Lake
12th Gen

RPi



Raspberry Pi5



DATA INTELLIGENCE DRAM MODULE NEW PRODUCT OVERVIEW



DDR5 7200MT/s

Edge AI Ultra-High-Speed Computing Engine

ADVANTAGES

World-leading, first-to-market DDR5 7200MT/s RDIMM built for ultra-high-speed, low-latency **AI and Edge Computing** workloads.

PROSPECTS

As DDR4 supply tightens and the market shifts to DDR5, Innodisk drives early penetration in **high-end Edge Computing and server switches**.



CXL AIC (ADD-IN-CARD)

Breaking Edge Computing's Memory Barrier

ADVANTAGES

Boost flexibility and scalable capacity to overcome edge-memory limits, delivering higher performance with cost efficiency.

PROSPECTS

Focused on **high-end edge-AI markets**, leveraging the synergy of CXL AIC and RDIMM integration.



DATA INTELLIGENCE FLASH STORAGE NEW PRODUCT OVERVIEW



ON-DEVICE SSD

Edge AI Single Edge Device



ON-PREM SSD

Enterprise AI Local Server

PRODUCT FEATURE

- Low latency / High Endurance / Real-time data collection, best-in-class storage for Edge AI applications
 - High capacity: 16TB (U.2) / 8TB (M.2)
 - Optimal thermal management
 - Device-level encryption and physical security
-
- High endurance for read/write-intensive and critical reliability fulfillment
 - Extremely high capacity: PCIe Gen5 128TB (QLC) and 32TB (eTLC)
 - Exceptional performance: 14,000/1,0000 MB/s
 - System-level encryption



CONNECTING INTELLIGENCE CAN BUS | NEW PRODUCT OVERVIEW



EGUC-F1S3

- M.2 2242 to Single Isolated CAN FD
- Input I/F: USB 2.0 Highspeed
- Output I/F: CAN FD
- Wide Temp: -40°C ~ 85°C



EGUC-F2S3

- M.2 2280 to Dual Isolated CAN FD
- Input I/F: USB 2.0 Highspeed
- Output I/F: CAN FD
- Wide Temp: -40°C ~ 85°C



ESPC-F4S3

- PCIe to dual isolated CAN FD
- Input I/F: PCI Express 2.0 x1
- Output I/F: CAN FD
- Wide Temp: -40°C ~ 85°C

INTELLIGENT CONNECTIVITY ENABLING DIVERSE APPLICATIONS

Ideal for robotics, mining, AGV/AMR, and industrial automation, delivering highly stable and efficient data communication.



Humanoid Robot



Mining



AGV/AMR



Industrial Automation



CONNECTING INTELLIGENCE

SFP NETWORKING | NEW PRODUCT OVERVIEW



EGPL-G1F1

- M.2 to Single GbE SFP Network Module
- Input I/F: PCI Express 2 x2
- Output I/F: SFP x1
- Wide Temp: -40°C ~ 85°C



EGPL-G2F1

- M.2 to Dual GbE SFP Network Module
- Input I/F: PCI Express 2 x2
- Output I/F: SFP x 2
- Wide Temp: -40°C ~ 85°C

FIBER PRECISION

EMPOWERING SMART INDUSTRIES

M.2 to SFP fiber modules with Intel i210-IS, supporting multi-mode and single-mode fiber. Ideal for smart manufacturing, surveillance, and edge-AI platforms requiring stable, high-performance networking.



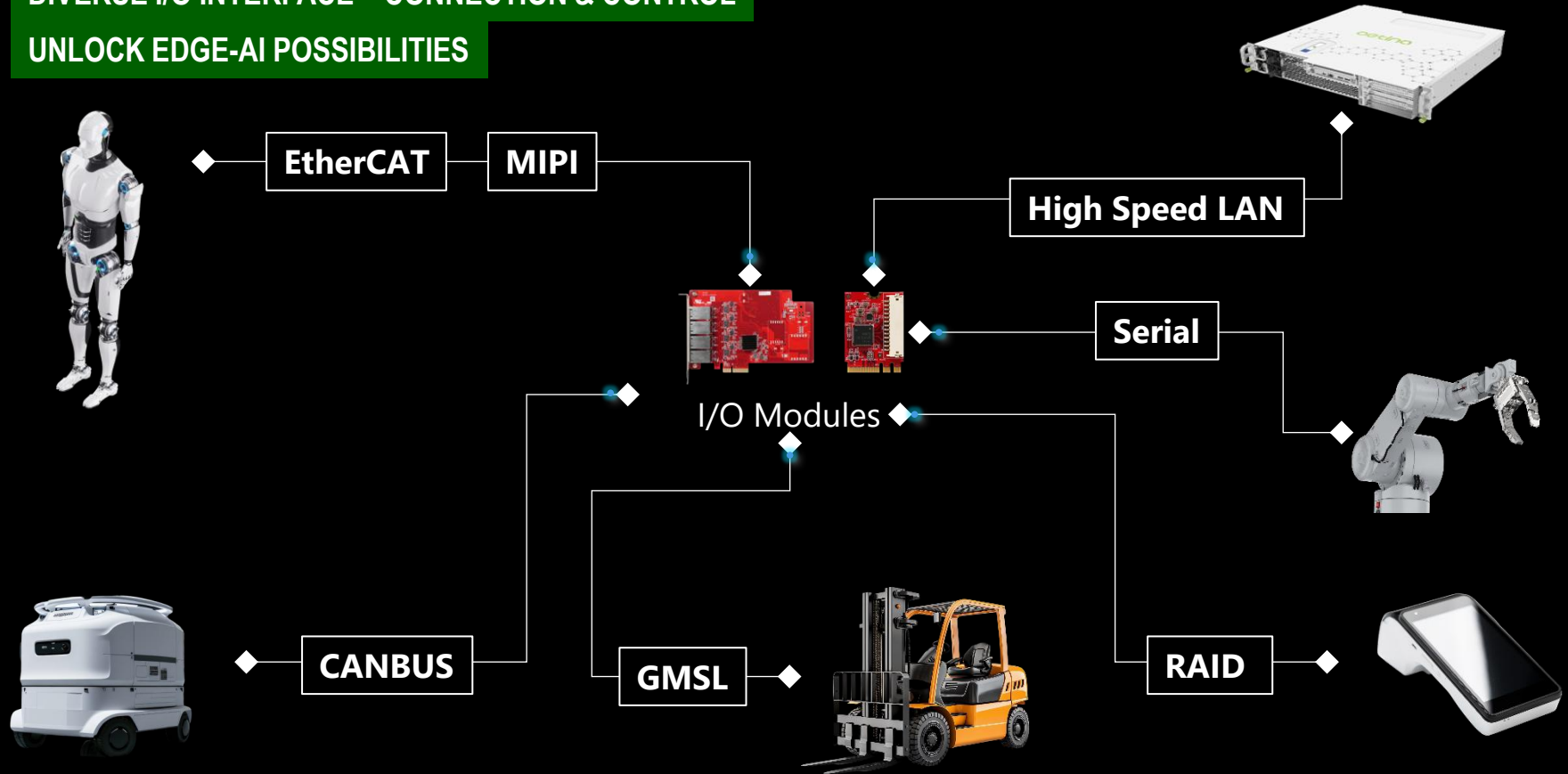
Edge AI Platform

Surveillance

Digital Signage

Industrial Automation

DIVERSE I/O INTERFACE – CONNECTION & CONTROL
UNLOCK EDGE-AI POSSIBILITIES





COMPUTING INTELLIGENCE NEW PRODUCT OVERVIEW



AIB-THOR-ES JETSON THOR T5000™ PREVIEW KITS

ADVANCING TOWARD CUTTING-EDGE ROBOTICS



Powerful AI Inference Processor

- CPU - 14 Cores ARM Poseidon-AE
- GPU – Blackwell Arch, 2560 CUDA Cores and 96 Fifth Generation Tensor Cores
- 2100 FP4 TFLOPS

Variety IO Support

- 2 x USB (Type-A & C)
- 26-pin CAN header,
- HDMI 2.0/DP 1.4a

Out-of-Box Performance

- 1 x QSFP28 up to 100GbE
- 1 x 5 GbE RJ45 Connector
- High DRAM BW – 256 bit LPDDR5X (up to 128GB Capacity)
- Audio DSP – 2 x Tensilica HiFi5 cores 16GMAC/sec

Comprehensive Expansion

- 2 x M.2 Key M with 1TB NVMe storage
- 1 x M.2 Key E with Wifi Module



COMPUTING INTELLIGENCE NEW PRODUCT OVERVIEW



EXMP-Q911

COM-HPC Mini powered by Qualcomm IQ-9075 SoC



EXMA-Q911

Module powered by Qualcomm IQ-9075M SoC

BUILDING THE QUALCOMM EDGE AI ECOSYSTEM HIGH PERFORMANCE, LOW POWER CONSUMPTION FOR EDGE AI



AGV/AMR

Machine Vision

Supports MIPI & GMSL camera integration



AI Smart Surveillance

AI Model Support

LLM / VLM / YoLo



Device Management

Software Support

Linux/Ubuntu/BSP/SDK



Customization Flexibility

Rich Peripheral Expansion

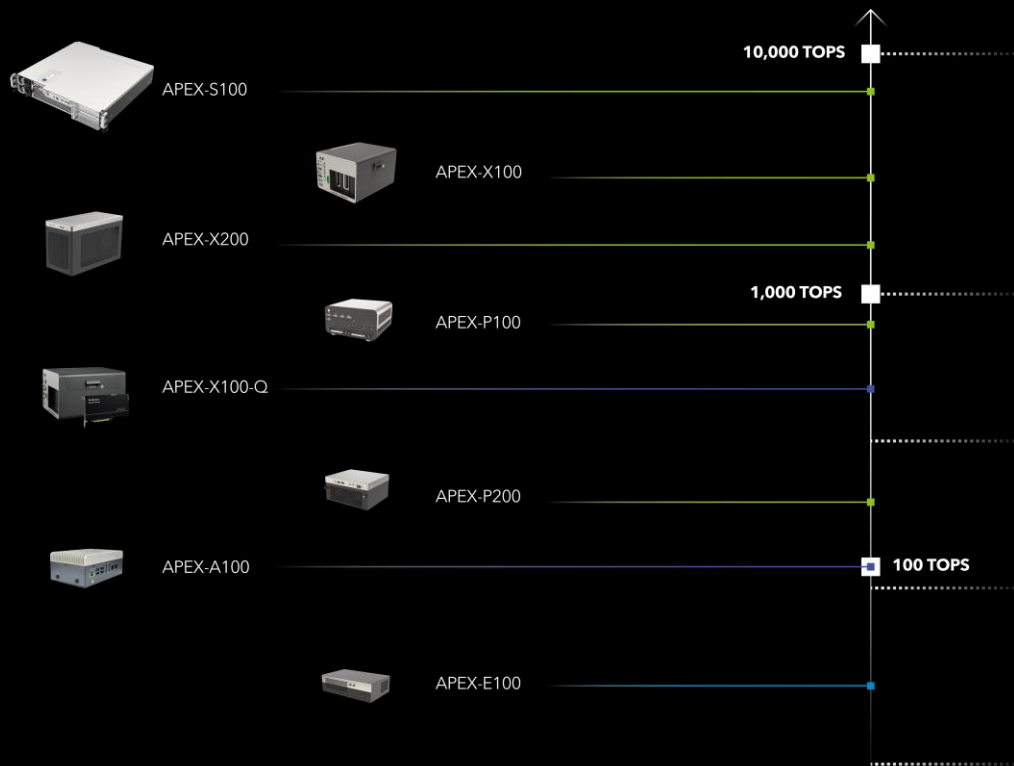
Industrial-grade SSDs and EP cards

The first COM-HPC Mini Type module powered by Qualcomm SoC — the IQ-9075 processor — delivers up to **100 TOPS** of AI performance with power consumption as low as **30W**. It integrates seamlessly with GMSL and MIPI cameras, CAN, and Serial expansion cards, enabling diverse edge AI applications such as visual recognition and vision-language models (VLM).



APPLIED INTELLIGENCE EDGE AI SYSTEM | APEX SERIES

Powered by  NVIDIA |  Qualcomm |  Intel



Advanced AI inference & model training

RAG and fine-tuning AI server for LLM/SLM/VLM

High-precision data analysis & large-scale AI inference

Advanced defect analytics, high-precision medical imaging

Mid-to-high performance image & speech analysis

ADAS, defect detection, medical imaging assistance

Low-power edge inference

Facial, object, and license-plate recognition

(TOPS @ INT8)



APPLIED INTELLIGENCE EDGE AI SYSTEM NEW PRODUCT OVERVIEW



APEX-S100 EDGE AI SERVER
ON-PREMISES LLM



INNODISK GROUP SOLUTIONS EMPOWERING ENTERPRISE EDGE AI



The diagram illustrates the Edge AI Host Architecture, showing the flow of data and processing across various layers and intelligence domains.

Intelligence Domains (Top):

- Retail Intelligence
- Surveillance Intelligence
- Enterprise & Building Intelligence
- Industrial Automation Intelligence

Business Logic Layer (Purple Border):

- iCAP
- iVIT
- innoPPE
- AccelBrain

Inter - Service Communication Layer (Blue Border):

- HTTP
- MQTT
- CoAP
- MCP

Host (Dark Grey Background):

- Service API Endpoint Layer (Light Blue Border):**
 - Device Management
 - AI Engine
 - Multi-Streaming
- Agentic AI Layer (Light Blue Border):**
 - MCP Server

Runtime Environment Layer (Orange Border):

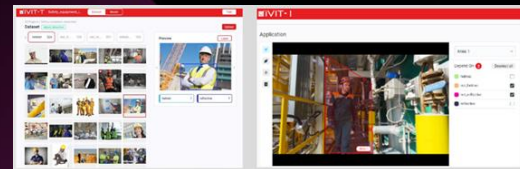
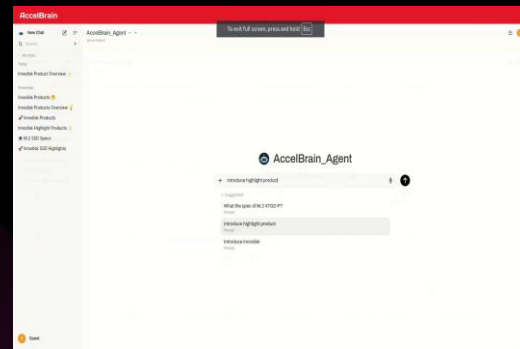
- HAL API

HW Module Adapter Layer (Green Border):

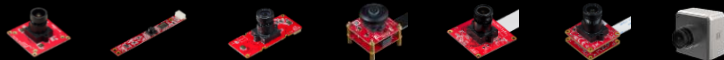
- eAPI
- CANBus Utility
- SSD SMART Utility
- SPD Code R/W

Flow Indicators:

- Upward arrow between Business Logic Layer and Inter - Service Communication Layer.
- Double-headed vertical arrow between Inter - Service Communication Layer and Host.
- Upward arrow between Host and Runtime Environment Layer.
- Upward arrow between Runtime Environment Layer and HW Module Adapter Layer.



INNODISK EDGE AI BUILDING BLOCKS

SOFTWARE / FIRMWARE	Cloud AI Platform	iCAP Remote Management / OOB / OTA / Recovery / Security / Diagnosis								
	AI-Stack Tool / SDK	iVIT	AccelBrain	AccelTune	AccelBrain(RAG) / AccelTune / iVIT-Training / iVIT-Inference					
	Software Tools	iSMART / iTracker / iOPAL / iRAID								
	Operating System	x86 / Arm, Window / Linux								
AI ACCELERATOR	NVIDIA	Intel		Qualcomm		AI ASIC				
										
AI PLATFORM	x86						Arm			
	Atom _X7000	12 th Gen Core-i	13/14 th Gen Core-i	Core Ultra Series1	Core Ultra Series 2	Core Ultra Series 3	Xeon 6	NVIDIA Jetson	Qualcom	AMD Xilinx
EMBEDDED PERIPHERAL	Flash	DRAM	Display	Storage	LAN	CAN Bus / CAN FD	GNSS	Wireless		
										
SENSOR	Embedded Camera Module						Air & Gas Sensor			
										

AI IN ACTION GLOBAL CAMPAIGN

AI BEYOND THE EDGE FORUM

@Taipei, Taiwan

- Date: 2025/10/22
- Attendance: **1,200** (online & offline)

innodisk

aetina

AXELERA
ARTIFICIAL INTELLIGENCE

鼎新數智

intel

KENMEC
AUTOMATION TECHNOLOGY

nvidia

Qualcomm



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ARTIFICIAL INTELLIGENCE

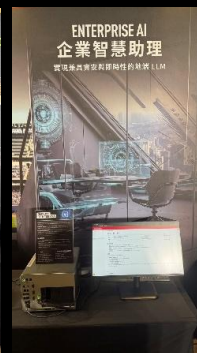
鼎新數智

intel.

KENMEC
AUTOMATION TECHNOLOGY

NVIDIA

Qualcomm



2025 COMPUTEX

@Taipei, Taiwan



FMS 2025

@California, USA



FMS25 - Taking on the FUTURE of Memory and Storage!

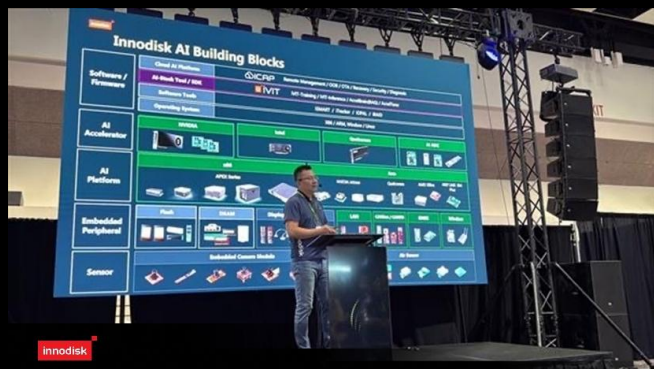


2025 BEST OF SHOW AWARD WINNER - INNODISK CXL MEMORY MODULE



AI INFRA SUMMIT 2025

@California, USA



INNODISK AI IN ACTION

Promote AI solutions with global partners



AI EXPO @TW



OTC @USA



Automate @USA



SPS @IT



Poland Seminar @PL



HPM @UK



Vision & Robotics @NL



SIDO @FR

ESG COMMITMENT



@WUWEIGANG WATERBIRD REFUGE, YILAN COUNTY

Ecological restoration / Habitat conservation / Windbreak afforestation / Community revitalization

@GREEN BAY, NEW TAPEI CITY

Marine conservation / Ocean education / Corporate family beach cleanups



2025 HIGHLIGHTS

- Maintaining a Corporate Governance Evaluation between **6% to 20%.**
- Approved by the Board of Directors, the company has set its Net Zero Emission Pathway, marking a proactive step toward long-term net-zero transition.
- Established the **"Sustainability Development & Information Security Committee"** to enhance ESG commitment.
- Received the EcoVadis Bronze Medal, Commonwealth Sustainability Awards, and the Parenting Family-Friendly Workplace Award, reflecting Innodisk's well-rounded achievements in sustainability.

2026 OBJECTIVES

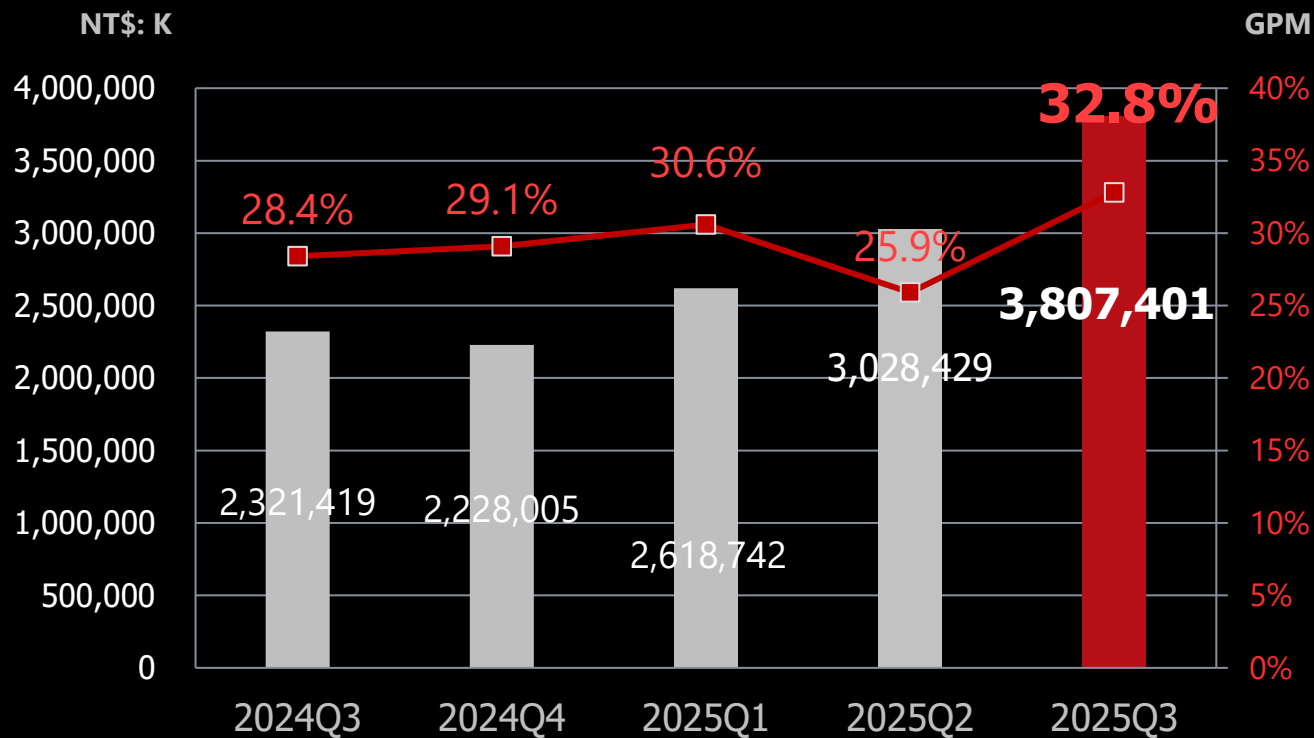
- Accelerated renewable energy transition and energy management efforts, delivering concrete carbon reduction results.
- Empowered employees and communities through inclusion and biodiversity programs.
- Reinforced sustainability governance and transparency in line with international frameworks such as IFRS.



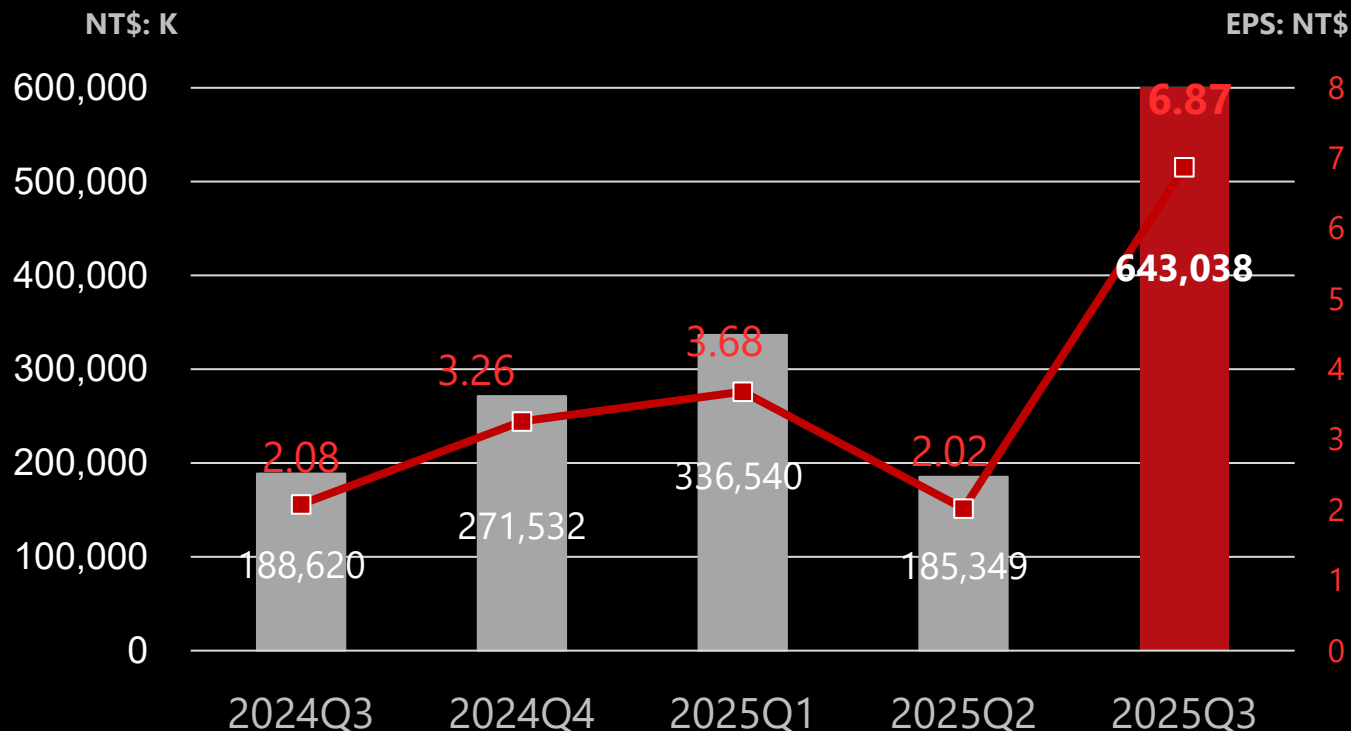
PATH TO SUSTAINABILITY

FINANCIAL INFORMATION

Revenues and GPM over last 5 quarters

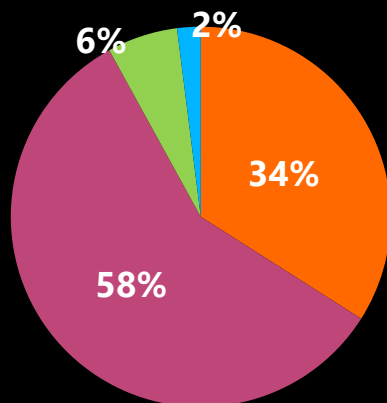


Net Profits and EPS over last 5 quarters

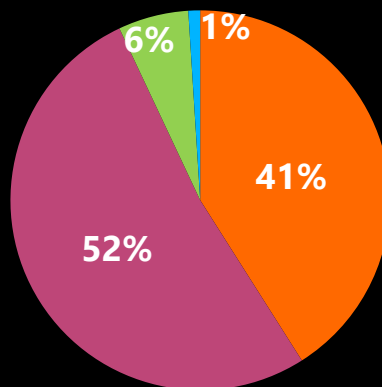


Revenue Breakdown by Product Lines

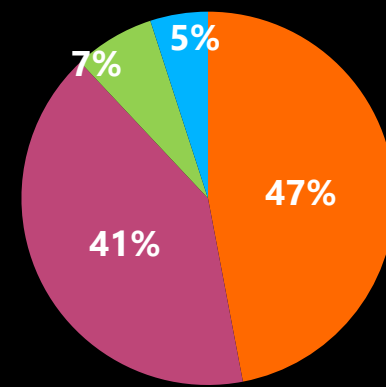
2025Q3



2025Q2



2024Q3



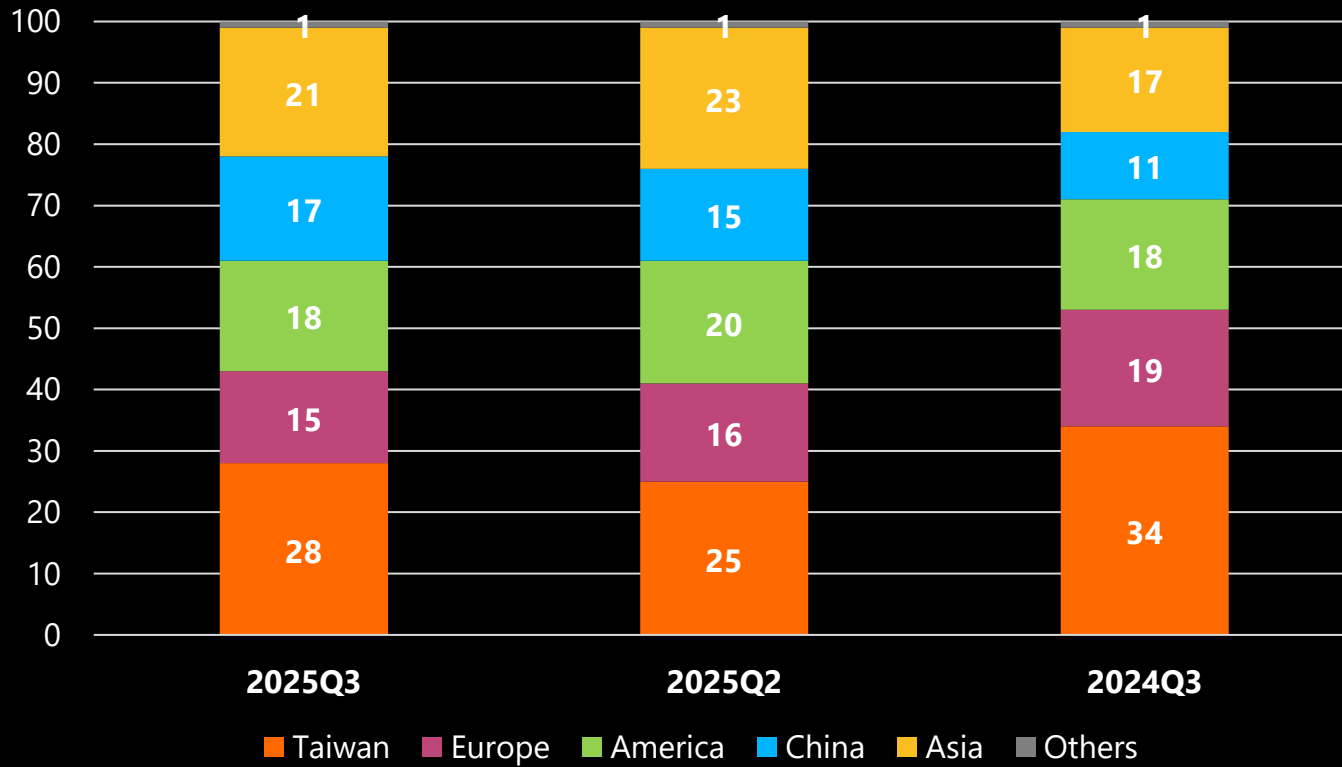
DRAM

Flash

AI Solutions

Others

Revenue Breakdown by Regions



Quarterly Income Statement

	2025Q3	2025Q2	QoQ	2024Q3	YoY
Revenues	3,807,401	3,028,429	25.7%	2,321,419	64.0%
Cost of good sold	2,558,583	2,243,340	14.1%	1,662,986	53.9%
Gross profit	1,248,818	785,089	59.1%	658,433	89.7%
Operation expenses	531,059	431,279	23.1%	413,237	28.5%
Operation profits	717,759	353,810	102.9%	245,196	192.7%
Non-operating income and expenses	88,738	-126,311	-170.3%	-11,351	-881.8%
Profit before tax	806,497	227,499	254.5%	233,845	244.9%
Income tax expense	163,923	53,708	205.2%	48,618	237.2%
Net profits	642,574	173,791	269.7%	185,227	246.9%
Non-controlling interests	-464	-11,558	-96.0%	-3,393	-86.3%
Net profit attributable to parent company	643,038	185,349	246.9%	188,620	240.9%
EPS	6.87	2.02		2.08	
Gross margin	32.8%	25.9%		28.4%	
Operating margin	18.9%	11.7%		10.6%	
Net profit rate	16.9%	5.7%		8.0%	

Q & A

